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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM7®
Core Size	16/32-Bit
Speed	44MHz
Connectivity	EBI/EMI, I²C, SPI, UART/USART
Peripherals	PLA, PWM, PSM, Temp Sensor, WDT
Number of I/O	22
Program Memory Size	62KB (31K x16)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 32
Voltage - Supply (Vcc/Vdd)	2.7V ~ 3.6V
Data Converters	A/D 7x12b; D/A 4x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	49-TFBGA, CSPBGA
Supplier Device Package	49-CSPBGA (5x5)
Purchase URL	https://www.e-xfl.com/product-detail/analog-devices/aduc7029bbcz62i

DETAILED BLOCK DIAGRAM

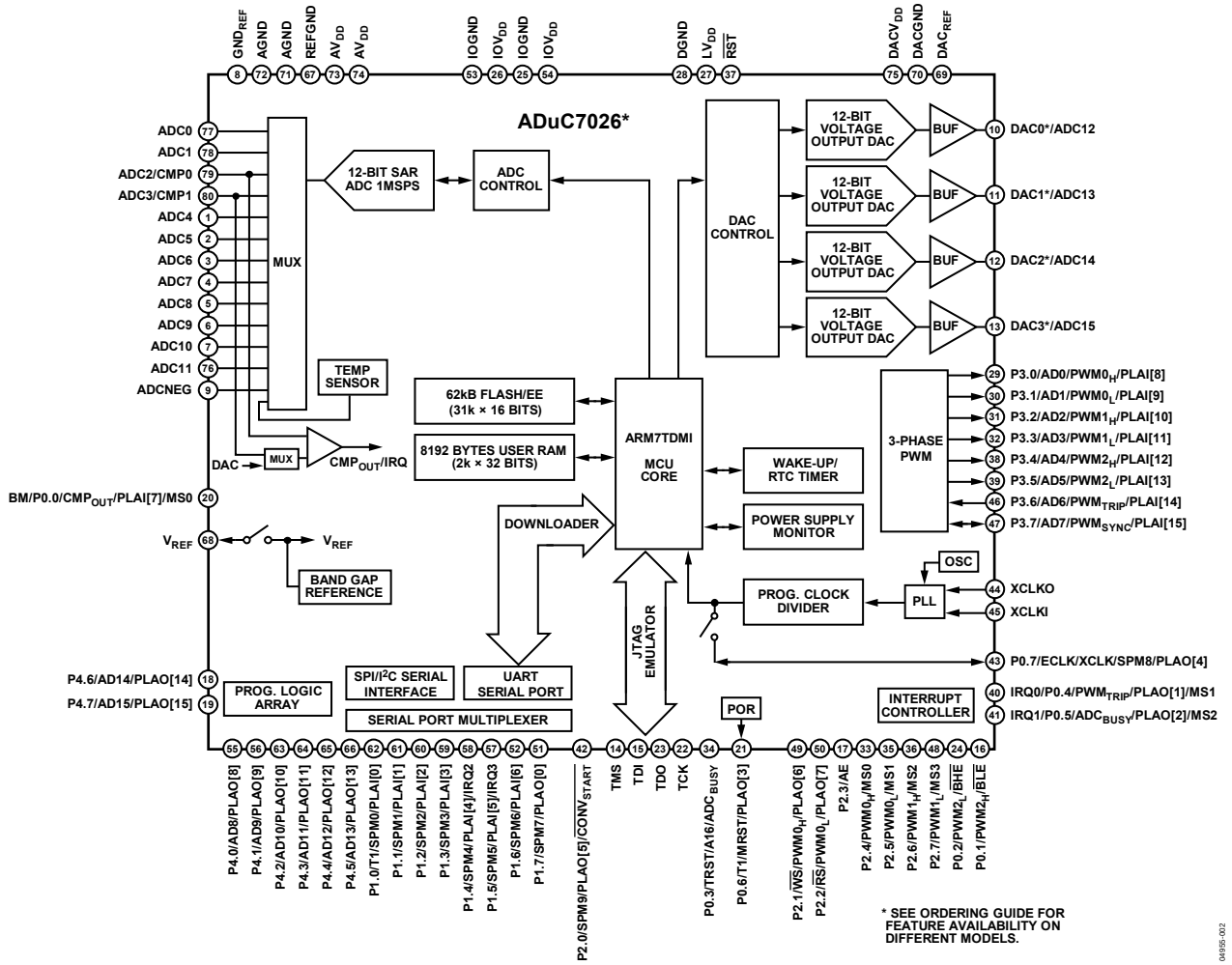


Figure 11.

SPECIFICATIONS

AV_{DD} = IOV_{DD} = 2.7 V to 3.6 V, V_{REF} = 2.5 V internal reference, f_{CORE} = 41.78 MHz, T_A = −40°C to +125°C, unless otherwise noted.

Table 1.

Parameter	Min	Typ	Max	Unit	Test Conditions/Comments
ADC CHANNEL SPECIFICATIONS					Eight acquisition clocks and fADC/2
ADC Power-Up Time		5		µs	
DC Accuracy[1, 2]					
Resolution	12			Bits	
Integral Nonlinearity		±0.6	±1.5	LSB	2.5 V internal reference
		±1.0		LSB	1.0 V external reference
Differential Nonlinearity[3, 4]		±0.5	+1/−0.9	LSB	2.5 V internal reference
		+0.7/−0.6		LSB	1.0 V external reference
DC Code Distribution		1		LSB	ADC input is a dc voltage
ENDPOINT ERRORS[5]					
Offset Error		±1	±2	LSB	
Offset Error Match		±1		LSB	
Gain Error		±2	±5	LSB	
Gain Error Match		±1		LSB	
DYNAMIC PERFORMANCE					f_{IN} = 10 kHz sine wave, f_{SAMPLE} = 1 MSPS
Signal-to-Noise Ratio (SNR)		69		dB	Includes distortion and noise components
Total Harmonic Distortion (THD)		−78		dB	
Peak Harmonic or Spurious Noise (PHSN)		−75		dB	
Channel-to-Channel Crosstalk		−80		dB	Measured on adjacent channels
ANALOG INPUT					
Input Voltage Ranges					
Differential Mode			V_{CM}[6] ± V_{REF}/2	V	
Single-Ended Mode			0 to V_{REF}	V	
Leakage Current		±1	±6	µA	
Input Capacitance		20		pF	During ADC acquisition
ON-CHIP VOLTAGE REFERENCE					0.47 µF from V_{REF} to AGND
Output Voltage		2.5		V	
Accuracy			±5	mV	T_A = 25°C
Reference Temperature Coefficient		±40		ppm/°C	
Power Supply Rejection Ratio		75		dB	
Output Impedance		70		Ω	T_A = 25°C
Internal V_{REF} Power-On Time		1		ms	
EXTERNAL REFERENCE INPUT					
Input Voltage Range	0.625		AV_{DD}	V	
DAC CHANNEL SPECIFICATIONS					R_L = 5 kΩ, C_L = 100 pF
DC Accuracy[7]					
Resolution		12		Bits	
Relative Accuracy		±2		LSB	
Differential Nonlinearity			±1	LSB	Guaranteed monotonic
Offset Error			±15	mV	2.5 V internal reference
Gain Error[8]			±1	%	
Gain Error Mismatch		0.1		%	% of full scale on DAC0
ANALOG OUTPUTS					
Output Voltage Range_0		0 to DAC_{REF}		V	DAC_{REF} range: DACGND to $DACV_{DD}$
Output Voltage Range_1		0 to 2.5		V	
Output Voltage Range_2		0 to $DACV_{DD}$		V	
Output Impedance		2		Ω	

ABSOLUTE MAXIMUM RATINGS

AGND = REFGND = DACGND = GND_{REF}, T_A = 25°C, unless otherwise noted.

Table 10.

Parameter	Rating
AV_{DD} to IOV_{DD}	−0.3 V to +0.3 V
AGND to DGND	−0.3 V to +0.3 V
IOV_{DD} to IOGND, AV_{DD} to AGND	−0.3 V to +6 V
Digital Input Voltage to IOGND	−0.3 V to +5.3 V
Digital Output Voltage to IOGND	−0.3 V to IOV_{DD} + 0.3 V
V_{REF} to AGND	−0.3 V to AV_{DD} + 0.3 V
Analog Inputs to AGND	−0.3 V to AV_{DD} + 0.3 V
Analog Outputs to AGND	−0.3 V to AV_{DD} + 0.3 V
Operating Temperature Range, Industrial	–40°C to +125°C
Storage Temperature Range	–65°C to +150°C
Junction Temperature	150°C
θ_{JA} Thermal Impedance	
40-Lead LFCSP	26°C/W
49-Ball CSP_BGA	80°C/W
64-Lead LFCSP	24°C/W
64-Ball CSP_BGA	75°C/W
64-Lead LQFP	47°C/W
80-Lead LQFP	38°C/W
Peak Solder Reflow Temperature	
SnPb Assemblies (10 sec to 30 sec)	240°C
RoHS Compliant Assemblies (20 sec to 40 sec)	260°C

Stresses at or above those listed under Absolute Maximum Ratings may cause permanent damage to the product. This is a stress rating only; functional operation of the product at these or any other conditions above those indicated in the operational section of this specification is not implied. Operation beyond the maximum operating conditions for extended periods may affect product reliability.

Only one absolute maximum rating can be applied at any one time.

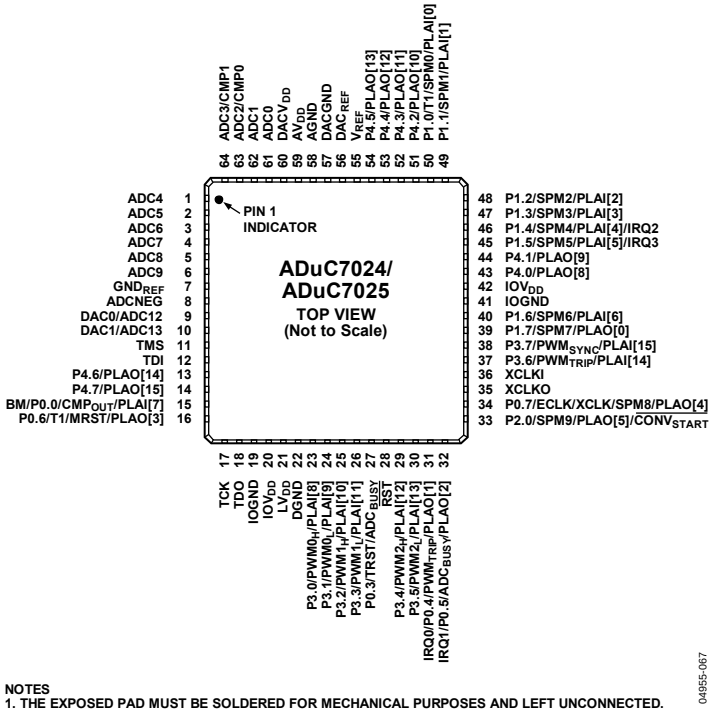
ESD CAUTION

ESD (electrostatic discharge) sensitive device. Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

Table 11. Pin Function Descriptions (ADuC7019/ADuC7020/ADuC7021/ADuC7022)

Pin No.				
7019/7020	7021	7022	Mnemonic	Description
38	37	36	ADC0	Single-Ended or Differential Analog Input 0.
39	38	37	ADC1	Single-Ended or Differential Analog Input 1.
40	39	38	ADC2/CMP0	Single-Ended or Differential Analog Input 2/Comparator Positive Input.
1	40	39	ADC3/CMP1	Single-Ended or Differential Analog Input 3 (Buffered Input on ADuC7019)/ Comparator Negative Input.
2	1	40	ADC4	Single-Ended or Differential Analog Input 4.
–	2	1	ADC5	Single-Ended or Differential Analog Input 5.
–	3	2	ADC6	Single-Ended or Differential Analog Input 6.
–	4	3	ADC7	Single-Ended or Differential Analog Input 7.
–	–	4	ADC8	Single-Ended or Differential Analog Input 8.
–	–	5	ADC9	Single-Ended or Differential Analog Input 9.
3	5	6	GND_{REF}	Ground Voltage Reference for the ADC. For optimal performance, the analog power supply should be separated from IOGND and DGND.
4	6	–	DAC0/ADC12	DAC0 Voltage Output/Single-Ended or Differential Analog Input 12.
5	7	–	DAC1/ADC13	DAC1 Voltage Output/Single-Ended or Differential Analog Input 13.
6	–	–	DAC2/ADC14	DAC2 Voltage Output/Single-Ended or Differential Analog Input 14.
7	–	–	DAC3/ADC15	DAC3 Voltage Output on ADuC7020. On the ADuC7019, a 10 nF capacitor must be connected between this pin and AGND/Single-Ended or Differential Analog Input 15 (see Figure 53).
8	8	7	TMS	Test Mode Select, JTAG Test Port Input. Debug and download access. This pin has an internal pull-up resistor to IOV_{DD}. In some cases, an external pull-up resistor (~100K) is also required to ensure that the part does not enter an erroneous state.
9	9	8	TDI	Test Data In, JTAG Test Port Input. Debug and download access.
10	10	9	BM/P0.0/CMP_{OUT}/PLAI[7]	Multifunction I/O Pin. Boot Mode (BM). The ADuC7019/20/21/22 enter serial download mode if BM is low at reset and execute code if BM is pulled high at reset through a 1 kΩ resistor/General-Purpose Input and Output Port 0.0/Voltage Comparator Output/Programmable Logic Array Input Element 7.
11	11	10	P0.6/T1/MRST/PLAO[3]	Multifunction Pin. Driven low after reset. General-Purpose Output Port 0.6/ Timer1 Input/Power-On Reset Output/Programmable Logic Array Output Element 3.
12	12	11	TCK	Test Clock, JTAG Test Port Input. Debug and download access. This pin has an internal pull-up resistor to IOV_{DD}. In some cases an external pull-up resistor (~100K) is also required to ensure that the part does not enter an erroneous state.
13	13	12	TDO	Test Data Out, JTAG Test Port Output. Debug and download access.
14	14	13	IOGND	Ground for GPIO (see Table 78). Typically connected to DGND.
15	15	14	IOV_{DD}	3.3 V Supply for GPIO (see Table 78) and Input of the On-Chip Voltage Regulator.
16	16	15	LV_{DD}	2.6 V Output of the On-Chip Voltage Regulator. This output must be connected to a 0.47 µF capacitor to DGND only.
17	17	16	DGND	Ground for Core Logic.
18	18	17	P0.3/TRST/ADC_{BUSY}	General-Purpose Input and Output Port 0.3/Test Reset, JTAG Test Port Input/ ADC_{BUSY} Signal Output.
19	19	18	$\overline{RST}$	Reset Input, Active Low.
20	20	19	IRQ0/P0.4/PWM_{TRIP}/PLAO[1]	Multifunction I/O Pin. External Interrupt Request 0, Active High/General-Purpose Input and Output Port 0.4/PWM Trip External Input/Programmable Logic Array Output Element 1.
21	21	20	IRQ1/P0.5/ADC_{BUSY}/PLAO[2]	Multifunction I/O Pin. External Interrupt Request 1, Active High/General-Purpose Input and Output Port 0.5/ADC_{BUSY} Signal Output/Programmable Logic Array Output Element 2.

ADuC7024/ADuC7025



NOTES
1. THE EXPOSED PAD MUST BE SOLDERED FOR MECHANICAL PURPOSES AND LEFT UNCONNECTED.

Figure 23. 64-Lead LFCSP_VQ Pin Configuration (ADuC7024/ADuC7025)

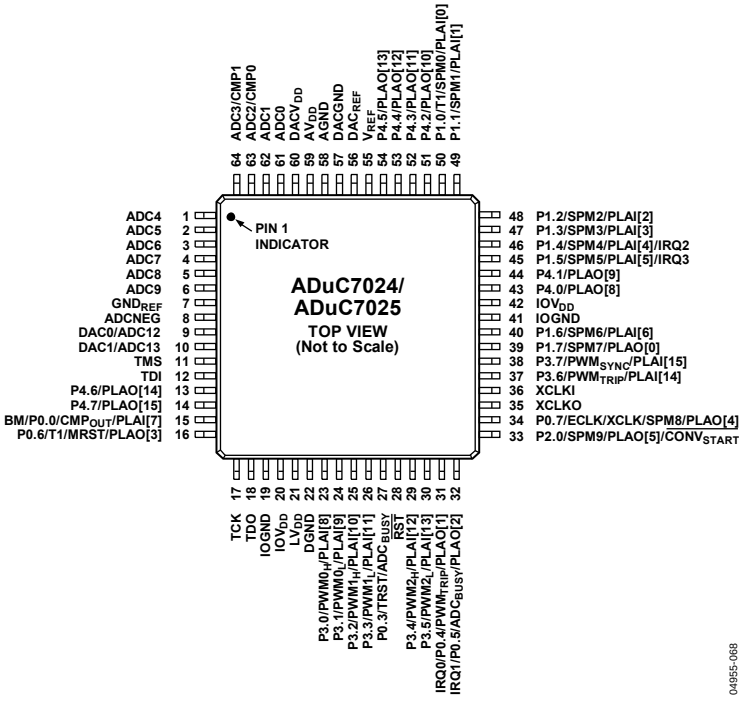


Figure 24. 64-Lead LQFP Pin Configuration (ADuC7024/ADuC7025)

TYPICAL PERFORMANCE CHARACTERISTICS

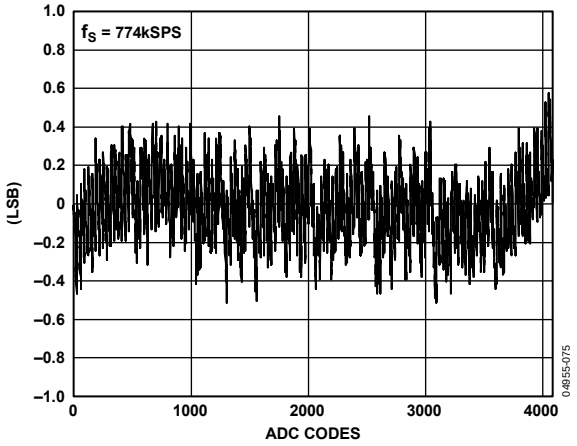


Figure 28. Typical INL Error, f_S = 774 kSPS

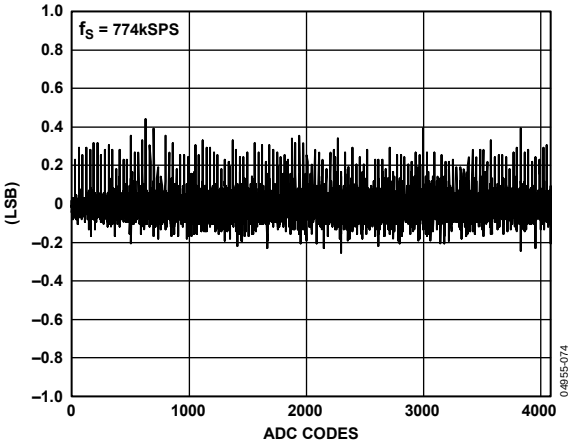


Figure 31. Typical DNL Error, f_S = 774 kSPS

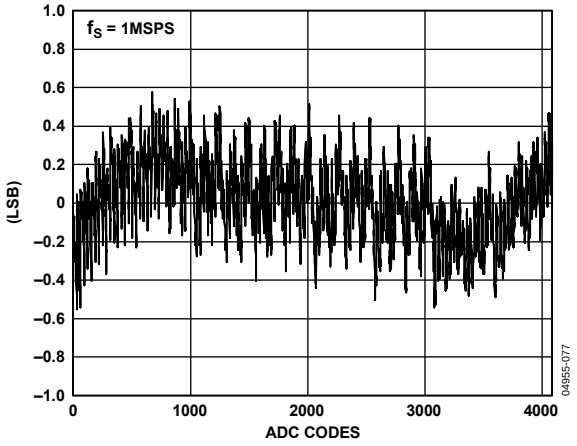


Figure 29. Typical INL Error, f_S = 1 MSPS

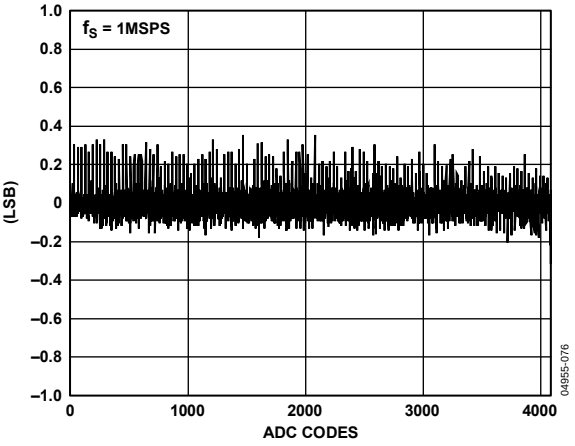


Figure 32. Typical DNL Error, f_S = 1 MSPS

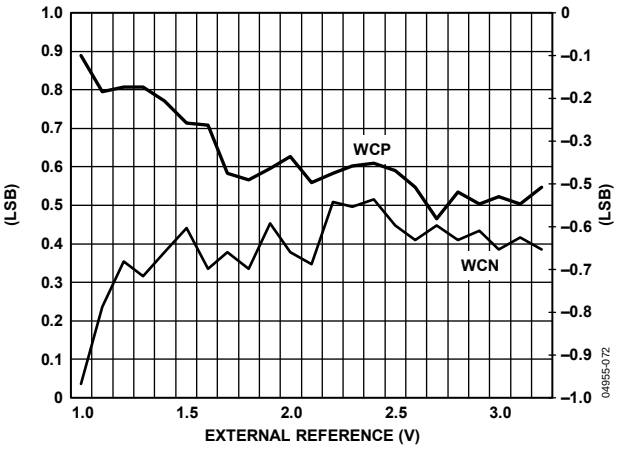


Figure 30. Typical Worst-Case (Positive (WCP) and Negative (WCN)) INL Error vs. V_{REF}, f_S = 774 kSPS

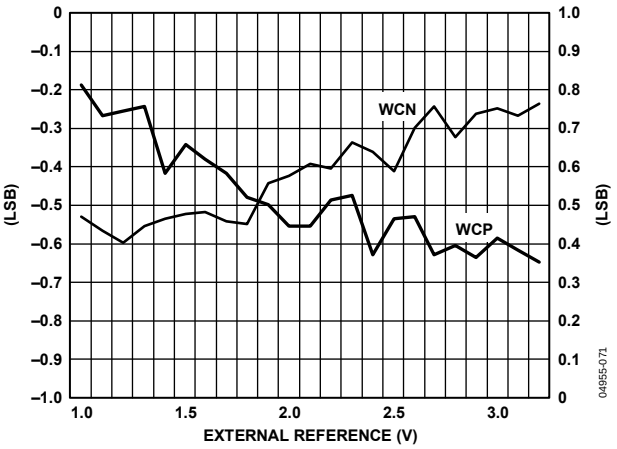


Figure 33. Typical Worst-Case (Positive (WCP)and Negative (WCN)) DNL Error vs. V_{REF}, f_S = 774 kSPS

MEMORY ORGANIZATION

The ADuC7019/20/21/22/24/25/26/27/28/29 incorporate two separate blocks of memory: 8 kB of SRAM and 64 kB of on-chip Flash/EE memory. The 62 kB of on-chip Flash/EE memory is available to the user, and the remaining 2 kB are reserved for the factory-configured boot page. These two blocks are mapped as shown in Figure 45.

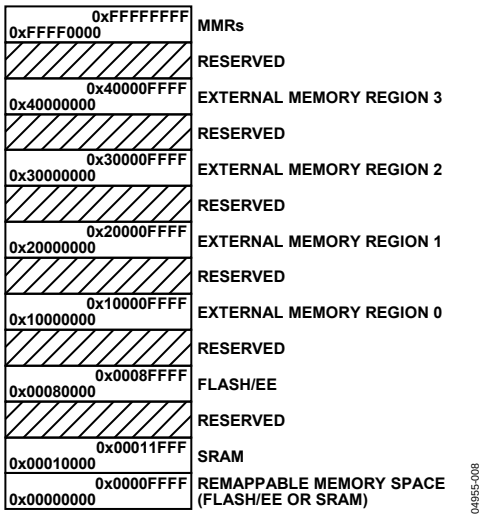


Figure 45. Physical Memory Map

Note that by default, after a reset, the Flash/EE memory is mirrored at Address 0x00000000. It is possible to remap the SRAM at Address 0x00000000 by clearing Bit 0 of the REMAP MMR. This remap function is described in more detail in the Flash/EE Memory section.

MEMORY ACCESS

The ARM7 core sees memory as a linear array of a 2^{32} byte location where the different blocks of memory are mapped as outlined in Figure 45.

The ADuC7019/20/21/22/24/25/26/27/28/29 memory organizations are configured in little endian format, which means that the least significant byte is located in the lowest byte address, and the most significant byte is in the highest byte address.

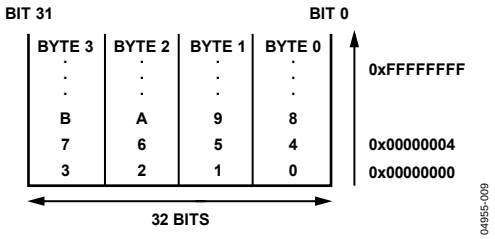


Figure 46. Little Endian Format

FLASH/EE MEMORY

The total 64 kB of Flash/EE memory is organized as 32 k × 16 bits; 31 k × 16 bits is user space and 1 k × 16 bits is reserved for the on-chip kernel. The page size of this Flash/EE memory is 512 bytes.

Sixty-two kilobytes of Flash/EE memory are available to the user as code and nonvolatile data memory. There is no distinction between data and program because ARM code shares the same space. The real width of the Flash/EE memory is 16 bits, which means that in ARM mode (32-bit instruction), two accesses to the Flash/EE are necessary for each instruction fetch. It is therefore recommended to use thumb mode when executing from Flash/EE memory for optimum access speed. The maximum access speed for the Flash/EE memory is 41.78 MHz in thumb mode and 20.89 MHz in full ARM mode. More details about Flash/EE access time are outlined in the Execution Time from SRAM and Flash/EE section.

SRAM

Eight kilobytes of SRAM are available to the user, organized as 2 k × 32 bits, that is, two words. ARM code can run directly from SRAM at 41.78 MHz, given that the SRAM array is configured as a 32-bit wide memory array. More details about SRAM access time are outlined in the Execution Time from SRAM and Flash/EE section.

MEMORY MAPPED REGISTERS

The memory mapped register (MMR) space is mapped into the upper two pages of the memory array and accessed by indirect addressing through the ARM7 banked registers.

The MMR space provides an interface between the CPU and all on-chip peripherals. All registers, except the core registers, reside in the MMR area. All shaded locations shown in Figure 47 are unoccupied or reserved locations and should not be accessed by user software. Table 16 shows the full MMR memory map.

The access time for reading from or writing to an MMR depends on the advanced microcontroller bus architecture (AMBA) bus used to access the peripheral. The processor has two AMBA buses: the advanced high performance bus (AHB) used for system modules and the advanced peripheral bus (APB) used for lower performance peripheral. Access to the AHB is one cycle, and access to the APB is two cycles. All peripherals on the ADuC7019/20/21/22/24/25/26/27/28/29 are on the APB except the Flash/EE memory, the GPIOs (see Table 78), and the PWM.

EXECUTION TIME FROM SRAM AND FLASH/EE

Execution from SRAM

Fetching instructions from SRAM takes one clock cycle; the access time of the SRAM is 2 ns, and a clock cycle is 22 ns minimum. However, if the instruction involves reading or writing data to memory, one extra cycle must be added if the data is in SRAM (or three cycles if the data is in Flash/EE): one cycle to execute the instruction, and two cycles to get the 32-bit data from Flash/EE. A control flow instruction (a branch instruction, for example) takes one cycle to fetch but also takes two cycles to fill the pipeline with the new instructions.

Execution from Flash/EE

Because the Flash/EE width is 16 bits and access time for 16-bit words is 22 ns, execution from Flash/EE cannot be done in one cycle (as can be done from SRAM when the CD Bit = 0). Also, some dead times are needed before accessing data for any value of the CD bit.

In ARM mode, where instructions are 32 bits, two cycles are needed to fetch any instruction when CD = 0. In thumb mode, where instructions are 16 bits, one cycle is needed to fetch any instruction.

Timing is identical in both modes when executing instructions that involve using the Flash/EE for data memory. If the instruction to be executed is a control flow instruction, an extra cycle is needed to decode the new address of the program counter, and then four cycles are needed to fill the pipeline. A data-processing instruction involving only the core register does not require any extra clock cycles. However, if it involves data in Flash/EE, an extra clock cycle is needed to decode the address of the data, and two cycles are needed to get the 32-bit data from Flash/EE. An extra cycle must also be added before fetching another instruction. Data transfer instructions are more complex and are summarized in Table 43.

Table 43. Execution Cycles in ARM/Thumb Mode

Instructions	Fetch Cycles	Dead Time	Data Access	Dead Time
LD[1]	2/1	1	2	1
LDH	2/1	1	1	1
LDM/PUSH	2/1	N[2]	2 × N[2]	N[1]
STR[1]	2/1	1	2 × 20 ns	1
STRH	2/1	1	20 ns	1
STRM/POP	2/1	N[1]	2 × N × 20 ns[1]	N[1]

[1] The SWAP instruction combines an LD and STR instruction with only one fetch, giving a total of eight cycles + 40 ns.
[2] N is the amount of data to load or store in the multiple load/store instruction (1 < N ≤ 16).

RESET AND REMAP

The ARM exception vectors are all situated at the bottom of the memory array, from Address 0x00000000 to Address 0x00000020, as shown in Figure 62.

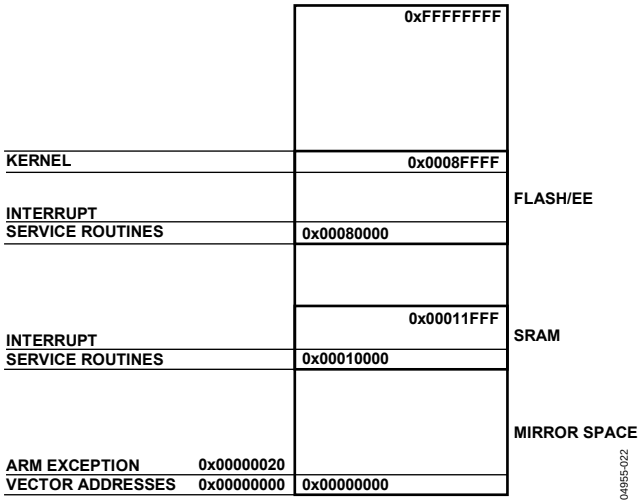


Figure 62. Remap for Exception Execution

By default, and after any reset, the Flash/EE is mirrored at the bottom of the memory array. The remap function allows the programmer to mirror the SRAM at the bottom of the memory array, which facilitates execution of exception routines from SRAM instead of from Flash/EE. This means exceptions are executed twice as fast, being executed in 32-bit ARM mode with 32-bit wide SRAM instead of 16-bit wide Flash/EE memory.

Remap Operation

When a reset occurs on the ADuC7019/20/21/22/24/25/26/27/28/29, execution automatically starts in the factory-programmed, internal configuration code. This kernel is hidden and cannot be accessed by user code. If the part is in normal mode (the BM pin is high), it executes the power-on configuration routine of the kernel and then jumps to the reset vector address, 0x00000000, to execute the user's reset exception routine.

Because the Flash/EE is mirrored at the bottom of the memory array at reset, the reset interrupt routine must always be written in Flash/EE.

The remap is done from Flash/EE by setting Bit 0 of the REMAP register. Caution must be taken to execute this command from Flash/EE, above Address 0x00080020, and not from the bottom of the array because this is replaced by the SRAM.

This operation is reversible. The Flash/EE can be remapped at Address 0x00000000 by clearing Bit 0 of the REMAP MMR. Caution must again be taken to execute the remap function from outside the mirrored area. Any type of reset remaps the Flash/EE memory at the bottom of the array.

DESCRIPTION OF THE PWM BLOCK

A functional block diagram of the PWM controller is shown in Figure 68. The generation of the six output PWM signals on Pin $PWM0_H$ to Pin $PWM2_L$ is controlled by the following four important blocks:

- The 3-phase PWM timing unit. The core of the PWM controller, this block generates three pairs of complemented and dead-time-adjusted, center-based PWM signals. This unit also generates the internal synchronization pulse, PWMSYNC. It also controls whether the external PWM_{SYNC} pin is used.
- The output control unit. This block can redirect the outputs of the 3-phase timing unit for each channel to either the high-side or low-side output. In addition, the output control unit allows individual enabling/disabling of each of the six PWM output signals.
- The gate drive unit. This block can generate the high frequency chopping and its subsequent mixing with the PWM signals.
- The PWM shutdown controller. This block controls the PWM shutdown via the PWM_{TRIP} pin and generates the correct reset signal for the timing unit.

The PWM controller is driven by the ADuC7019/20/21/22/24/25/26/27/28/29 core clock frequency and is capable of generating two interrupts to the ARM core. One interrupt is generated on the occurrence of a PWMSYNC pulse, and the other is generated on the occurrence of any PWM shutdown action.

3-Phase Timing Unit

PWM Switching Frequency (PWMDAT0 MMR)

The PWM switching frequency is controlled by the PWM period register, PWMDAT0. The fundamental timing unit of the PWM controller is

$$t_{CORE} = 1/f_{CORE}$$

where f_{CORE} is the core frequency of the MicroConverter.

Therefore, for a 41.78 MHz f_{CORE}, the fundamental time increment is 24 ns. The value written to the PWMDAT0 register is effectively the number of f_{CORE} clock increments in one-half a PWM period. The required PWMDAT0 value is a function of the desired PWM switching frequency (f_{PWN}) and is given by

$$PWMDAT0 = f_{CORE}/(2 \times f_{PWM})$$

Therefore, the PWM switching period, t_S, can be written as

$$t_S = 2 \times PWMDAT0 \times t_{CORE}$$

The largest value that can be written to the 16-bit PWMDAT0 MMR is 0xFFFF = 65,535, which corresponds to a minimum PWM switching frequency of

$$f_{PWM(min)} = 41.78 \times 10^6/(2 \times 65{,}535) = 318.75 \text{ Hz}$$

Note that PWMDAT0 values of 0 and 1 are not defined and should not be used.

PWM Switching Dead Time (PWMDAT1 MMR)

The second important parameter that must be set up in the initial configuration of the PWM block is the switching dead time. This is a short delay time introduced between turning off one PWM signal (0H, for example) and turning on the complementary signal (0L). This short time delay is introduced to permit the power switch to be turned off (in this case, 0H) to completely recover its blocking capability before the complementary switch is turned on. This time delay prevents a potentially destructive short-circuit condition from developing across the dc link capacitor of a typical voltage source inverter.

The dead time is controlled by the 10-bit, read/write PWMDAT1 register. There is only one dead-time register that controls the dead time inserted into all three pairs of PWM output signals. The dead time, t_D, is related to the value in the PWMDAT1 register by

$$t_D = PWMDAT1 \times 2 \times t_{CORE}$$

Therefore, a PWMDAT1 value of 0x00A (= 10), introduces a 426 ns delay between the turn-off on any PWM signal (0H, for example) and the turn-on of its complementary signal (0L). The amount of the dead time can, therefore, be programmed in increments of $2t_{CORE}$ (or 49 ns for a 41.78 MHz core clock).

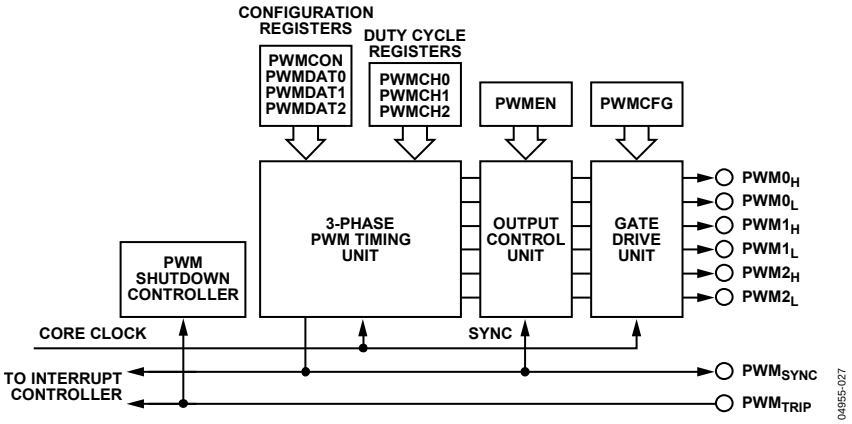


Figure 68. Overview of the PWM Controller

Output Control Unit

The operation of the output control unit is controlled by the 9-bit read/write PWMEN register. This register controls two distinct features of the output control unit that are directly useful in the control of electronic counter measures (ECM) or binary decimal counter measures (BDCM). The PWMEN register contains three crossover bits, one for each pair of PWM outputs. Setting Bit 8 of the PWMEN register enables the crossover mode for the 0H/0L pair of PWM signals, setting Bit 7 enables crossover on the 1H/1L pair of PWM signals, and setting Bit 6 enables crossover on the 2H/2L pair of PWM signals. If crossover mode is enabled for any pair of PWM signals, the high-side PWM signal from the timing unit (0H, for example) is diverted to the associated low-side output of the output control unit so that the signal ultimately appears at the $PWM0_L$ pin. Of course, the corresponding low-side output of the timing unit is also diverted to the complementary high-side output of the output control unit so that the signal appears at the $PWM0_H$ pin. Following a reset, the three crossover bits are cleared, and the crossover mode is disabled on all three pairs of PWM signals. The PWMEN register also contains six bits (Bit 0 to Bit 5) that can be used to individually enable or disable each of the six PWM outputs. If the associated bit of the PWMEN register is set, the corresponding PWM output is disabled regardless of the corresponding value of the duty cycle register. This PWM output signal remains in the off state as long as the corresponding enable/disable bit of the PWMEN register is set. The implementation of this output enable function is implemented after the crossover function.

Following a reset, all six enable bits of the PWMEN register are cleared, and all PWM outputs are enabled by default. In a manner identical to the duty cycle registers, the PWMEN is latched on the rising edge of the PWMSYNC signal. As a result, changes to this register become effective only at the start of each PWM cycle in single update mode. In double update mode, the PWMEN register can also be updated at the midpoint of the PWM cycle.

In the control of an ECM, only two inverter legs are switched at any time, and often the high-side device in one leg must be switched on at the same time as the low-side driver in a second leg. Therefore, by programming identical duty cycle values for two PWM channels (for example, PWMCH0 = PWMCH1) and setting Bit 7 of the PWMEN register to cross over the 1H/1L pair of PWM signals, it is possible to turn on the high-side switch of Phase A and the low-side switch of Phase B at the same time. In the control of ECM, it is usual for the third inverter leg (Phase C in this example) to be disabled for a number of PWM cycles. This function is implemented by disabling both the 2H and 2L PWM outputs by setting Bit 0 and Bit 1 of the PWMEN register.

This situation is illustrated in Figure 71, where it can be seen that both the 0H and 1L signals are identical because PWMCH0 = PWMCH1 and the crossover bit for Phase B is set.

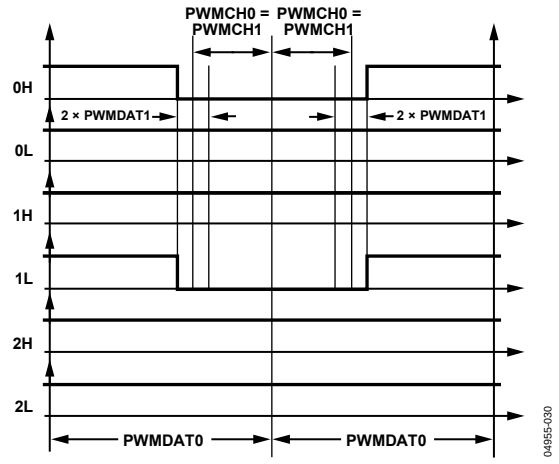


Figure 71. Active Low PWM Signals Suitable for ECM Control, PWMCH0 = PWMCH1, Crossover 1H/1L Pair and Disable 0L, 1H, 2H, and 2L Outputs in Single Update Mode.

In addition, the other four signals (0L, 1H, 2H, and 2L) have been disabled by setting the appropriate enable/disable bits of the PWMEN register. In Figure 71, the appropriate value for the PWMEN register is 0x00A7. In normal ECM operation, each inverter leg is disabled for certain periods of time to change the PWMEN register based on the position of the rotor shaft (motor commutation).

Gate Drive Unit

The gate drive unit of the PWM controller adds features that simplify the design of isolated gate-drive circuits for PWM inverters. If a transformer-coupled, power device, gate-drive amplifier is used, the active PWM signal must be chopped at a high frequency. The 16-bit read/write PWMCFG register programs this high frequency chopping mode. The chopped active PWM signals can be required for the high-side drivers only, the low-side drivers only, or both the high-side and low-side switches. Therefore, independent control of this mode for both high-side and low-side switches is included with two separate control bits in the PWMCFG register.

Typical PWM output signals with high frequency chopping enabled on both high-side and low-side signals are shown in Figure 72. Chopping of the high-side PWM outputs (0H, 1H, and 2H) is enabled by setting Bit 8 of the PWMCFG register. Chopping of the low-side PWM outputs (0L, 1L, and 2L) is enabled by setting Bit 9 of the PWMCFG register. The high chopping frequency is controlled by the 8-bit word (GDCLK) placed in Bit 0 to Bit 7 of the PWMCFG register. The period of this high frequency carrier is

$$t_{CHOP} = (4 \times (GDCLK + 1)) \times t_{CORE}$$

The chopping frequency is, therefore, an integral subdivision of the MicroConverter core frequency

$$f_{CHOP} = f_{CORE}/(4 \times (GDCLK + 1))$$

The GDCLK value can range from 0 to 255, corresponding to a programmable chopping frequency rate of 40.8 kHz to 10.44 MHz for a 41.78 MHz core frequency. The gate drive features must be programmed before operation of the PWM controller and are typically not changed during normal operation of the PWM controller. Following a reset, all bits of the PWMCFG register are cleared so that high frequency chopping is disabled, by default.

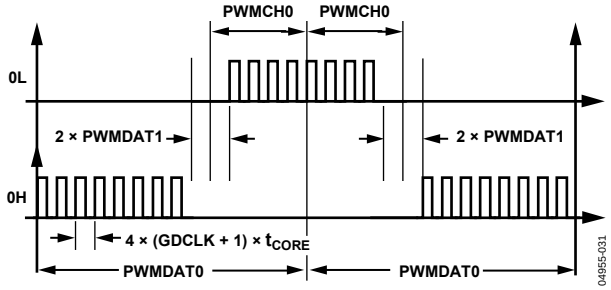


Figure 72. Typical PWM Signals with High Frequency Gate Chopping Enabled on Both High-Side and Low-Side Switches

PWM Shutdown

In the event of external fault conditions, it is essential that the PWM system be instantaneously shut down in a safe fashion. A low level on the PWM_{TRIP} pin provides an instantaneous, asynchronous (independent of the MicroConverter core clock) shutdown of the PWM controller. All six PWM outputs are placed in the off state, that is, in low state. In addition, the PWMSYNC pulse is disabled. The PWM_{TRIP} pin has an internal pull-down resistor to disable the PWM if the pin becomes disconnected. The state of the PWM_{TRIP} pin can be read from Bit 3 of the PWMSTA register.

If a PWM shutdown command occurs, a PWMTRIP interrupt is generated, and internal timing of the 3-phase timing unit of the PWM controller is stopped. Following a PWM shutdown, the PWM can be reenabled (in a PWMTRIP interrupt service routine, for example) only by writing to all of the PWMDAT0, PWMCH0, PWMCH1, and PWMCH2 registers. Provided that the external fault is cleared and the PWMTRIP is returned to a high level, the internal timing of the 3-phase timing unit resumes, and new duty-cycle values are latched on the next PWMSYNC boundary.

Note that the PWMTRIP interrupt is available in IRQ only, and the PWMSYNC interrupt is available in FIQ only. Both interrupts share the same bit in the interrupt controller. Therefore, only one of the interrupts can be used at a time. See the Interrupt System section for further details.

PWM MMRs Interface

The PWM block is controlled via the MMRs described in this section.

Table 66. PWMCON Register

Name	Address	Default Value	Access
PWMCON	0xFFFFFC00	0x0000	R/W

PWMCON is a control register that enables the PWM and chooses the update rate.

Table 67. PWMCON MMR Bit Descriptions

Bit	Name	Description
7:5		Reserved.
4	PWM_SYNCSEL	External sync select. Set to use external sync. Cleared to use internal sync.
3	PWM_EXTSYNC	External sync select. Set to select external synchronous sync signal. Cleared for asynchronous sync signal.
2	PWMDBL	Double update mode. Set to 1 by user to enable double update mode. Cleared to 0 by the user to enable single update mode.
1	PWM_SYNC_EN	PWM synchronization enable. Set by user to enable synchronization. Cleared by user to disable synchronization.
0	PWMEN	PWM enable bit. Set to 1 by user to enable the PWM. Cleared to 0 by user to disable the PWM. Also cleared automatically with PWMTRIP (PWMSTA MMR).

Table 68. PWMSTA Register

Name	Address	Default Value	Access
PWMSTA	0xFFFFFC04	0x0000	R/W

PWMSTA reflects the status of the PWM.

Table 69. PWMSTA MMR Bit Descriptions

Bit	Name	Description
15:10		Reserved.
9	PWMSYNCINT	PWM sync interrupt bit. Writing a 1 to this bit clears this interrupt.
8	PWMTRIPINT	PWM trip interrupt bit. Writing a 1 to this bit clears this interrupt.
3	PWMTRIP	Raw signal from the PWM_{TRIP} pin.
2:1		Reserved.
0	PWMPHASE	PWM phase bit. Set to 1 by the MicroConverter when the timer is counting down (first half). Cleared to 0 by the MicroConverter when the timer is counting up (second half).

Table 70. PWMCFG Register

Name	Address	Default Value	Access
PWMCFG	0xFFFFFC10	0x0000	R/W

PWMCFG is a gate chopping register.

Table 71. PWMCFG MMR Bit Descriptions

Bit	Name	Description
15:10		Reserved.
9	CHOPLO	Low-side gate chopping enable bit.
8	CHOPHI	High-side gate chopping enable bit.
7:0	GDCLK	PWM gate chopping period (unsigned).

Table 72. PWMEN Register

Name	Address	Default Value	Access
PWMEN	0xFFFFFC20	0x0000	R/W

PWMEN allows enabling of channel outputs and crossover. See its bit definitions in Table 73.

Table 73. PWMEN MMR Bit Descriptions

Bit	Name	Description
8	0H0L_XOVR	Channel 0 output crossover enable bit. Set to 1 by user to enable Channel 0 output crossover. Cleared to 0 by user to disable Channel 0 output crossover.
7	1H1L_XOVR	Channel 1 output crossover enable bit. Set to 1 by user to enable Channel 1 output crossover. Cleared to 0 by user to disable Channel 1 output crossover.
6	2H2L_XOVR	Channel 2 output crossover enable bit. Set to 1 by user to enable Channel 2 output crossover. Cleared to 0 by user to disable Channel 2 output crossover.
5	0L_EN	0L output enable bit. Set to 1 by user to disable the 0L output of the PWM. Cleared to 0 by user to enable the 0L output of the PWM.
4	0H_EN	0H output enable bit. Set to 1 by user to disable the 0H output of the PWM. Cleared to 0 by user to enable the 0H output of the PWM.
3	1L_EN	1L output enable bit. Set to 1 by user to disable the 1L output of the PWM. Cleared to 0 by user to enable the 1L output of the PWM.
2	1H_EN	1H Output Enable Bit. Set to 1 by user to disable the 1H output of the PWM. Cleared to 0 by user to enable the 1H output of the PWM.
1	2L_EN	2L output enable bit. Set to 1 by user to disable the 2L output of the PWM. Cleared to 0 by user to enable the 2L output of the PWM.
0	2H_EN	2H output enable bit. Set to 1 by user to disable the 2H output of the PWM. Cleared to 0 by user to enable the 2H output of the PWM.

Table 74. PWMDAT0 Register

Name	Address	Default Value	Access
PWMDAT0	0xFFFFFC08	0x0000	R/W

PWMDAT0 is an unsigned 16-bit register for switching period.

Table 75. PWMDAT1 Register

Name	Address	Default Value	Access
PWMDAT1	0xFFFFFC0C	0x0000	R/W

PWMDAT1 is an unsigned 10-bit register for dead time.

Table 76. PWMCHx Registers

Name	Address	Default Value	Access
PWMCH0	0xFFFFFC14	0x0000	R/W
PWMCH1	0xFFFFFC18	0x0000	R/W
PWMCH2	0xFFFFFC1C	0x0000	R/W

PWMCH0, PWMCH1, and PWMCH2 are channel duty cycles for the three phases.

Table 77. PWMDAT2 Register

Name	Address	Default Value	Access
PWMDAT2	0xFFFFFC24	0x0000	R/W

PWMDAT2 is an unsigned 10-bit register for PWM sync pulse width.

GENERAL-PURPOSE INPUT/OUTPUT

The ADuC7019/20/21/22/24/25/26/27/28/29 provide 40 general-purpose, bidirectional I/O (GPIO) pins. All I/O pins are 5 V tolerant, meaning the GPIOs support an input voltage of 5 V.

In general, many of the GPIO pins have multiple functions (see Table 78 for the pin function definitions). By default, the GPIO pins are configured in GPIO mode.

All GPIO pins have an internal pull-up resistor (of about 100 kΩ), and their drive capability is 1.6 mA. Note that a maximum of 20 GPIOs can drive 1.6 mA at the same time. Using the GPxPAR registers, it is possible to enable/disable the pull-up resistors for the following ports: P0.0, P0.4, P0.5, P0.6, P0.7, and the eight GPIOs of P1.

The 40 GPIOs are grouped in five ports, Port 0 to Port 4 (Port x). Each port is controlled by four or five MMRs.

Note that the kernel changes P0.6 from its default configuration at reset (MRST) to GPIO mode. If MRST is used for external circuitry, an external pull-up resistor should be used to ensure that the level on P0.6 does not drop when the kernel switches mode. Otherwise, P0.6 goes low for the reset period. For example, if MRST is required for power-down, it can be reconfigured in GP0CON MMR.

The input level of any GPIO can be read at any time in the GPxDAT MMR, even when the pin is configured in a mode other than GPIO. The PLA input is always active.

When the ADuC7019/20/21/22/24/25/26/27/28/29 part enters a power-saving mode, the GPIO pins retain their state.

Table 116. COMIID1 MMR Bit Descriptions

Bit 3:1 Status Bits	Bit 0 NINT	Priority	Definition	Clearing Operation
000	1		No interrupt	
110	0	2	Matching network address	Read COMRX
101	0	3	Address transmitted, buffer empty	Write data to COMTX or read COMIID0
011	0	1	Receive line status interrupt	Read COMSTA0
010	0	2	Receive buffer full interrupt	Read COMRX
001	0	3	Transmit buffer empty interrupt	Write data to COMTX or read COMIID0
000	0	4	Modem status interrupt	Read COMSTA1

Note that to receive a network address interrupt, the slave must ensure that Bit 0 of COMIEN0 (enable receive buffer full interrupt) is set to 1.

Table 117. COMADR Register

Name	Address	Default Value	Access
COMADR	0xFFFF0728	0xAA	R/W

COMADR is an 8-bit, read/write network address register that holds the address checked for by the network addressable UART. Upon receiving this address, the device interrupts the processor and/or sets the appropriate status bit in COMIID1.

SERIAL PERIPHERAL INTERFACE

The ADuC7019/20/21/22/24/25/26/27/28/29 integrate a complete hardware serial peripheral interface (SPI) on-chip. SPI is an industry standard, synchronous serial interface that allows eight bits of data to be synchronously transmitted and simultaneously received, that is, full duplex up to a maximum bit rate of 3.48 Mb, as shown in Table 118. The SPI interface is not operational with core clock divider (CD) bits. POWCON[2:0] = 6 or 7 in master mode.

The SPI port can be configured for master or slave operation. and typically consists of four pins: MISO (P1.5), MOSI (P1.6), SCLK (P1.4), and $\overline{CS}$ (P1.7).

On the transmit side, the SPITX register (and a TX shift register outside it) loads data onto the transmit pin (in slave mode, MISO; in master mode, MOSI). The transmit status bit, Bit 0, in SPISTA indicates whether there is valid data in the SPITX register.

Similarly, the receive data path consists of the SPIRX register (and an RX shift register). SPISTA, Bit 3 indicates whether there is valid data in the SPIRX register. If valid data in the SPIRX register is overwritten or if valid data in the RX shift register is discarded, SPISTA, Bit 5 (the overflow bit) is set.

MISO (Master In, Slave Out) Pin

The MISO pin is configured as an input line in master mode and an output line in slave mode. The MISO line on the master (data in) should be connected to the MISO line in the slave device (data out). The data is transferred as byte wide (8-bit) serial data, MSB first.

MOSI (Master Out, Slave In) Pin

The MOSI pin is configured as an output line in master mode and an input line in slave mode. The MOSI line on the master (data out) should be connected to the MOSI line in the slave device (data in). The data is transferred as byte wide (8-bit) serial data, MSB first.

SCLK (Serial Clock I/O) Pin

The master serial clock (SCLK) is used to synchronize the data being transmitted and received through the MOSI SCLK period. Therefore, a byte is transmitted/received after eight SCLK periods. The SCLK pin is configured as an output in master mode and as an input in slave mode.

In master mode, the polarity and phase of the clock are controlled by the SPICON register, and the bit rate is defined in the SPIDIV register as follows:

$$f_{SERIAL\,CLOCK} = \frac{f_{UCLK}}{2\times(1+SPIDIV)}$$

The maximum speed of the SPI clock is dependent on the clock divider bits and is summarized in Table 118.

Table 118. SPI Speed vs. Clock Divider Bits in Master Mode

CD Bits	0	1	2	3	4	5
SPIDIV in Hex	0x05	0x0B	0x17	0x2F	0x5F	0xBF
SPI dpeed in MHz	3.482	1.741	0.870	0.435	0.218	0.109

In slave mode, the SPICON register must be configured with the phase and polarity of the expected input clock. The slave accepts data from an external master up to 10.4 Mb at CD = 0. The formula to determine the maximum speed is as follows:

$$f_{SERIAL\,CLOCK} = \frac{f_{HCLK}}{4}$$

In both master and slave modes, data is transmitted on one edge of the SCL signal and sampled on the other. Therefore, it is important that the polarity and phase be configured the same for the master and slave devices.

Chip Select ($\overline{CS}$ Input) Pin

In SPI slave mode, a transfer is initiated by the assertion of $\overline{CS}$, which is an active low input signal. The SPI port then transmits and receives 8-bit data until the transfer is concluded by deassertion of $\overline{CS}$. In slave mode, $\overline{CS}$ is always an input.

SPI Registers

The following MMR registers are used to control the SPI interface: SPISTA, SPIRX, SPITX, SPIDIV, and SPICON.

Table 119. SPISTA Register

Name	Address	Default Value	Access
SPISTA	0xFFFF0A00	0x00	R

SPISTA is an 8-bit read-only status register. Only Bit 1 or Bit 4 of this register generates an interrupt. Bit 6 of the SPICON register determines which bit generates the interrupt.

Table 120. SPISTA MMR Bit Descriptions

Bit	Description
7:6	Reserved.
5	SPIRX data register overflow status bit. Set if SPIRX is overflowing. Cleared by reading the SPIRX register.
4	SPIRX data register IRQ. Set automatically if Bit 3 or Bit 5 is set. Cleared by reading the SPIRX register.
3	SPIRX data register full status bit. Set automatically if a valid data is present in the SPIRX register. Cleared by reading the SPIRX register.
2	SPITX data register underflow status bit. Set automatically if SPITX is underflowing. Cleared by writing in the SPITX register.
1	SPITX data register IRQ. Set automatically if Bit 0 is clear or Bit 2 is set. Cleared by writing in the SPITX register or if finished transmission disabling the SPI.
0	SPITX data register empty status bit. Set by writing to SPITX to send data. This bit is set during transmission of data. Cleared when SPITX is empty.

Table 121. SPIRX Register

Name	Address	Default Value	Access
SPIRX	0xFFFF0A04	0x00	R

SPIRX is an 8-bit, read-only receive register.

Table 122. SPITX Register

Name	Address	Default Value	Access
SPITX	0xFFFF0A08	0x00	W

SPITX is an 8-bit, write-only transmit register.

Table 123. SPIDIV Register

Name	Address	Default Value	Access
SPIDIV	0xFFFF0A0C	0x1B	R/W

SPIDIV is an 8-bit, serial clock divider register.

Table 124. SPICON Register

Name	Address	Default Value	Access
SPICON	0xFFFF0A10	0x0000	R/W

SPICON is a 16-bit control register.

Table 125. SPICON MMR Bit Descriptions

Bit	Description	Function
15:13	Reserved	N/A
12	Continuous transfer enable	Set by user to enable continuous transfer. In master mode, the transfer continues until no valid data is available in the TX register. $\overline{CS}$ is asserted and remains asserted for the duration of each 8-bit serial transfer until TX is empty. Cleared by user to disable continuous transfer. Each transfer consists of a single 8-bit serial transfer. If valid data exists in the SPITX register, then a new transfer is initiated after a stall period.
11	Loop back enable	Set by user to connect MISO to MOSI and test software. Cleared by user to be in normal mode.
10	Slave MISO output enable	Set this bit to disable the output driver on the MISO pin. The MISO pin becomes open drain when this bit is set. Clear this bit for MISO to operate as normal.
9	Clip select output enable	Set by user in master mode to disable the chip select output. cleared by user to enable the chip select output. P1.7 should be configured as $\overline{CS}$ before SPICON is configured as a master when the chip select output enabled is also selected.
8	SPIRX overflow overwrite enable	Set by user, the valid data in the RX register is overwritten by the new serial byte received. Cleared by user, the new serial byte received is discarded.
7	SPITX underflow mode	Set by user to transmit 0. Cleared by user to transmit the previous data.
6	Transfer and interrupt mode	Set by user to initiate transfer with a write to the SPITX register. Interrupt occurs only when TX is empty. Cleared by user to initiate transfer with a read of the SPIRX register. Interrupt occurs only when RX is full.
5	LSB first transfer enable bit	Set by user, the LSB is transmitted first. Cleared by user, the MSB is transmitted first.
4	Reserved	
3	Serial clock polarity mode bit	Set by user, the serial clock idles high. Cleared by user, the serial clock idles low.
2	Serial clock phase mode bit	Set by user, the serial clock pulses at the beginning of each serial bit transfer. Cleared by user, the serial clock pulses at the end of each serial bit transfer.
1	Master mode enable bit	Set by user to enable master mode. Cleared by user to enable slave mode.
0	SPI enable bit	Set by user to enable the SPI. Cleared by user to disable the SPI.

I²C-COMPATIBLE INTERFACES

The ADuC7019/20/21/22/24/25/26/27/28/29 support two licensed I²C interfaces. The I²C interfaces are both implemented as a hard-ware master and a full slave interface. Because the two I²C inter-faces are identical, this data sheet describes only I2C0 in detail. Note that the two masters and one of the slaves have individual interrupts (see the Interrupt System section).

Note that when configured as an I²C master device, the ADuC7019/20/21/22/24/25/26/27/28/29 cannot generate a repeated start condition.

The two GPIO pins used for data transfer, SDAx and SCLx, are configured in a wired-AND format that allows arbitration in a multimaster system. These pins require external pull-up resistors. Typical pull-up values are 10 kΩ.

The I²C bus peripheral address in the I²C bus system is programmed by the user. This ID can be modified any time a transfer is not in progress. The user can configure the interface to respond to four slave addresses.

The transfer sequence of an I²C system consists of a master device initiating a transfer by generating a start condition while the bus is idle. The master transmits the slave device address and the direction of the data transfer during the initial address transfer. If the master does not lose arbitration and the slave acknowledges, the data transfer is initiated. This continues until the master issues a stop condition and the bus becomes idle.

The I²C peripheral can be configured only as a master or slave at any given time. The same I²C channel cannot simultaneously support master and slave modes.

Serial Clock Generation

The I²C master in the system generates the serial clock for a transfer. The master channel can be configured to operate in fast mode (400 kHz) or standard mode (100 kHz).

The bit rate is defined in the I2C0DIV MMR as follows:

$$f_{SERIAL\ CLOCK} = \frac{f_{UCLK}}{(2 + DIVH) + (2 + DIVL)}$$

where:
f_{UCLK} = clock before the clock divider.
$DIVH$ = the high period of the clock.
$DIVL$ = the low period of the clock.

Thus, for 100 kHz operation,

$DIVH = DIVL$ = 0xCF

and for 400 kHz,

$DIVH$ = 0x28, $DIVL$ = 0x3C

The I2CxDIV registers correspond to DIVH:DIVL.

Slave Addresses

The registers I2C0ID0, I2C0ID1, I2C0ID2, and I2C0ID3 contain the device IDs. The device compares the four I2C0IDx registers to the address byte. To be correctly addressed, the seven MSBs of either ID register must be identical to that of the seven MSBs of the first received address byte. The LSB of the ID registers (the transfer direction bit) is ignored in the process of address recognition.

I²C Registers

The I²C peripheral interface consists of 18 MMRs, which are discussed in this section.

Table 126. I2CxMSTA Registers

Name	Address	Default Value	Access
I2C0MSTA	0xFFFF0800	0x00	R/W
I2C1MSTA	0xFFFF0900	0x00	R/W

I2CxMSTA are status registers for the master channel.

Table 127. I2C0MSTA MMR Bit Descriptions

Bit	Access Type	Description
7	R/W	Master transmit FIFO flush. Set by user to flush the master Tx FIFO. Cleared automatically after the master Tx FIFO is flushed. This bit also flushes the slave receive FIFO.
6	R	Master busy. Set automatically if the master is busy. Cleared automatically.
5	R	Arbitration loss. Set in multimaster mode if another master has the bus. Cleared when the bus becomes available.
4	R	No ACK. Set automatically if there is no acknowledge of the address by the slave device. Cleared automatically by reading the I2C0MSTA register.
3	R	Master receive IRQ. Set after receiving data. Cleared automatically by reading the I2C0MRX register.
2	R	Master transmit IRQ. Set at the end of a transmission. Cleared automatically by writing to the I2C0MTX register.
1	R	Master transmit FIFO underflow. Set automatically if the master transmit FIFO is underflowing. Cleared automatically by writing to the I2C0MTX register.
0	R	Master TX FIFO not full. Set automatically if the slave transmit FIFO is not full. Cleared automatically by writing twice to the I2C0STX register.

Table 128. I2CxSSTA Registers

Name	Address	Default Value	Access
I2C0SSTA	0xFFFF0804	0x01	R
I2C1SSTA	0xFFFF0904	0x01	R

I2CxSSTA are status registers for the slave channel.

PROGRAMMABLE LOGIC ARRAY (PLA)

Every ADuC7019/20/21/22/24/25/26/27/28/29 integrates a fully programmable logic array (PLA) that consists of two independent but interconnected PLA blocks. Each block consists of eight PLA elements, giving each part a total of 16 PLA elements.

Each PLA element contains a two-input lookup table that can be configured to generate any logic output function based on two inputs and a flip-flop. This is represented in Figure 76.

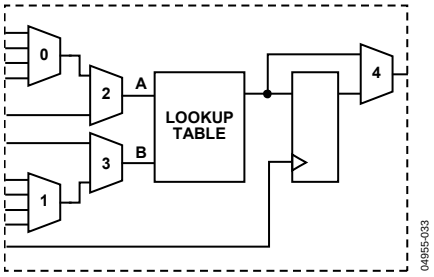


Figure 76. PLA Element

In total, 30 GPIO pins are available on each ADuC7019/20/21/22/24/25/26/27/28/29 for the PLA. These include 16 input pins and 14 output pins, which msut be configured in the GPxCON register as PLA pins before using the PLA. Note that the comparator output is also included as one of the 16 input pins.

The PLA is configured via a set of user MMRs. The output(s) of the PLA can be routed to the internal interrupt system, to the $\overline{\text{CONV}}_{\text{START}}$ signal of the ADC, to an MMR, or to any of the 16 PLA output pins.

The two blocks can be interconnected as follows:

- Output of Element 15 (Block 1) can be fed back to Input 0 of Mux 0 of Element 0 (Block 0).
- Output of Element 7 (Block 0) can be fed back to the Input 0 of Mux 0 of Element 8 (Block 1).

Table 145. Element Input/Output

PLA Block 0			PLA Block 1		
Element	**Input**	**Output**	**Element**	**Input**	**Output**
0	P1.0	P1.7	8	P3.0	P4.0
1	P1.1	P0.4	9	P3.1	P4.1
2	P1.2	P0.5	10	P3.2	P4.2
3	P1.3	P0.6	11	P3.3	P4.3
4	P1.4	P0.7	12	P3.4	P4.4
5	P1.5	P2.0	13	P3.5	P4.5
6	P1.6	P2.1	14	P3.6	P4.6
7	P0.0	P2.2	15	P3.7	P4.7

PLA MMRs Interface

The PLA peripheral interface consists of the 22 MMRs described in this section.

Table 146. PLAELMx Registers

Name	Address	Default Value	Access
PLAELM0	0xFFFF0B00	0x0000	R/W
PLAELM1	0xFFFF0B04	0x0000	R/W
PLAELM2	0xFFFF0B08	0x0000	R/W
PLAELM3	0xFFFF0B0C	0x0000	R/W
PLAELM4	0xFFFF0B10	0x0000	R/W
PLAELM5	0xFFFF0B14	0x0000	R/W
PLAELM6	0xFFFF0B18	0x0000	R/W
PLAELM7	0xFFFF0B1C	0x0000	R/W
PLAELM8	0xFFFF0B20	0x0000	R/W
PLAELM9	0xFFFF0B24	0x0000	R/W
PLAELM10	0xFFFF0B28	0x0000	R/W
PLAELM11	0xFFFF0B2C	0x0000	R/W
PLAELM12	0xFFFF0B30	0x0000	R/W
PLAELM13	0xFFFF0B34	0x0000	R/W
PLAELM14	0xFFFF0B38	0x0000	R/W
PLAELM15	0xFFFF0B3C	0x0000	R/W

PLAELMx are Element 0 to Element 15 control registers. They configure the input and output mux of each element, select the function in the lookup table, and bypass/use the flip-flop. See Table 147 and Table 152.

Table 147. PLAELMx MMR Bit Descriptions

Bit	Value	Description
31:11		Reserved.
10:9		Mux 0 control (see Table 152).
8:7		Mux 1 control (see Table 152).
6		Mux 2 control. Set by user to select the output of Mux 0. Cleared by user to select the bit value from PLADIN.
5		Mux 3 control. Set by user to select the input pin of the particular element. Cleared by user to select the output of Mux 1.
4:1		Lookup table control.
	0000	0.
	0001	NOR.
	0010	B AND NOT A.
	0011	NOT A.
	0100	A AND NOT B.
	0101	NOT B.
	0110	EXOR.
	0111	NAND.
	1000	AND.
	1001	EXNOR.
	1010	B.
	1011	NOT A OR B.
	1100	A.
	1101	A OR NOT B.
	1110	OR.
	1111	1.
0		Mux 4 control. Set by user to bypass the flip-flop. Cleared by user to select the flip-flop (cleared by default).

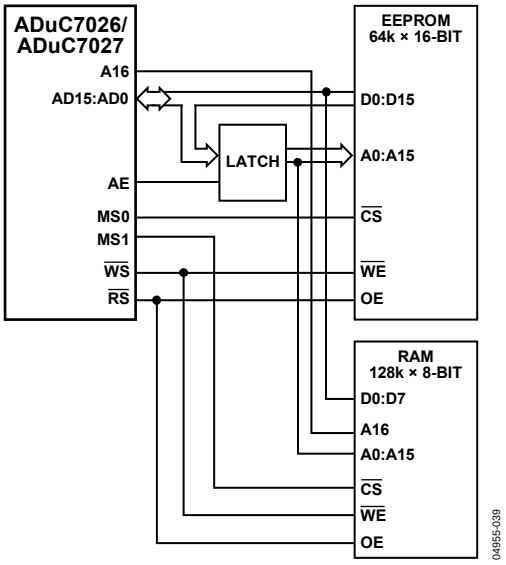


Figure 82. Interfacing to External EEPROM/RAM

Table 195. XMCFG Register

Name	Address	Default Value	Access
XMCFG	0xFFFFF000	0x00	R/W

XMCFG is set to 1 to enable external memory access. This must be set to 1 before any port pins function as external memory access pins. The port pins must also be individually enabled via the GPxCON MMR.

Table 196. XMxCON Registers

Name	Address	Default Value	Access
XM0CON	0xFFFFF010	0x00	R/W
XM1CON	0xFFFFF014	0x00	R/W
XM2CON	0xFFFFF018	0x00	R/W
XM3CON	0xFFFFF01C	0x00	R/W

XMxCON are the control registers for each memory region. They allow the enabling/disabling of a memory region and control the data bus width of the memory region.

Table 197. XMxCON MMR Bit Descriptions

Bit	Description
1	Selects data bus width. Set by user to select a 16-bit data bus. Cleared by user to select an 8-bit data bus.
0	Enables memory region. Set by user to enable the memory region. Cleared by user to disable the memory region.

Table 198. XMxPAR Registers

Name	Address	Default Value	Access
XM0PAR	0xFFFFF020	0x70FF	R/W
XM1PAR	0xFFFFF024	0x70FF	R/W
XM2PAR	0xFFFFF028	0x70FF	R/W
XM3PAR	0xFFFFF02C	0x70FF	R/W

XMxPAR are registers that define the protocol used for accessing the external memory for each memory region.

Table 199. XMxPAR MMR Bit Descriptions

Bit	Description
15	Enable byte write strobe. This bit is used only for two, 8-bit memory devices sharing the same memory region. Set by the user to gate the A0 output with the $\overline{WS}$ output. This allows byte write capability without using $\overline{BHE}$ and $\overline{BLE}$ signals. Cleared by user to use $\overline{BHE}$ and $\overline{BLE}$ signals.
14:12	Number of wait states on the address latch enable STROBE.
11	Reserved.
10	Extra address hold time. Set by user to disable extra hold time. Cleared by user to enable one clock cycle of hold on the address in read and write.
9	Extra bus transition time on read. Set by user to disable extra bus transition time. Cleared by user to enable one extra clock before and after the read strobe ($\overline{RS}$).
8	Extra bus transition time on write. Set by user to disable extra bus transition time. Cleared by user to enable one extra clock before and after the write strobe ($\overline{WS}$).
7:4	Number of write wait states. Select the number of wait states added to the length of the $\overline{WS}$ pulse. 0x0 is 1 clock; 0xF is 16 clock cycles (default value).
3:0	Number of read wait states. Select the number of wait states added to the length of the $\overline{RS}$ pulse. 0x0 is 1 clock; 0xF is 16 clock cycles (default value).

Figure 83, Figure 84, Figure 85, and Figure 86 show the timing for a read cycle, a read cycle with address hold and bus turn cycles, a write cycle with address and write hold cycles, and a write cycle with wait sates, respectively.

GROUNDING AND BOARD LAYOUT RECOMMENDATIONS

As with all high resolution data converters, special attention must be paid to grounding and PC board layout of the ADuC7019/20/21/22/24/25/26/27/28/29-based designs to achieve optimum performance from the ADCs and DAC.

Although the parts have separate pins for analog and digital ground (AGND and IOGND), the user must not tie these to two separate ground planes unless the two ground planes are connected very close to the part. This is illustrated in the simplified example shown in Figure 91a. In systems where digital and analog ground planes are connected together somewhere else (at the system power supply, for example), the planes cannot be reconnected near the part because a ground loop results. In these cases, tie all the ADuC7019/20/21/22/24/25/26/27/28/29 AGND and IOGND pins to the analog ground plane, as illustrated in Figure 91b. In systems with only one ground plane, ensure that the digital and analog components are physically separated onto separate halves of the board so that digital return currents do not flow near analog circuitry (and vice versa).

The ADuC7019/20/21/22/24/25/26/27/28/29 can then be placed between the digital and analog sections, as illustrated in Figure 91c.

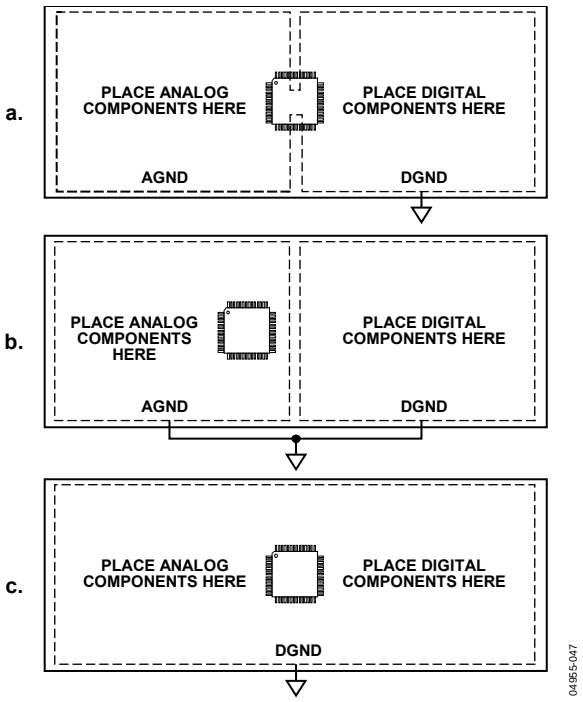


Figure 91. System Grounding Schemes

In all of these scenarios, and in more complicated real-life applications, the user should pay particular attention to the flow of current from the supplies and back to ground. Make sure the return paths for all currents are as close as possible to the paths the currents took to reach their destinations.

For example, do not power components on the analog side (as seen in Figure 91b) with IOV_{DD} because that forces return currents from IOV_{DD} to flow through AGND. Avoid digital currents flowing under analog circuitry, which can occur if a noisy digital chip is placed on the left half of the board (shown in Figure 91c). If possible, avoid large discontinuities in the ground plane(s) such as those formed by a long trace on the same layer because they force return signals to travel a longer path. In addition, make all connections to the ground plane directly, with little or no trace separating the pin from its via to ground.

When connecting fast logic signals (rise/fall time < 5 ns) to any of the ADuC7019/20/21/22/24/25/26/27/28/29 digital inputs, add a series resistor to each relevant line to keep rise and fall times longer than 5 ns at the part's input pins. A value of 100 Ω or 200 Ω is usually sufficient to prevent high speed signals from coupling capacitively into the part and affecting the accuracy of ADC conversions.

CLOCK OSCILLATOR

The clock source for the ADuC7019/20/21/22/24/25/26/27/28/29 can be generated by the internal PLL or by an external clock input. To use the internal PLL, connect a 32.768 kHz parallel resonant crystal between XCLKI and XCLKO, and connect a capacitor from each pin to ground as shown in Figure 92. The crystal allows the PLL to lock correctly to give a frequency of 41.78 MHz. If no external crystal is present, the internal oscillator is used to give a typical frequency of 41.78 MHz ± 3%.

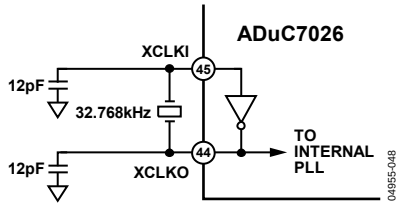


Figure 92. External Parallel Resonant Crystal Connections

To use an external source clock input instead of the PLL (see Figure 93), Bit 1 and Bit 0 of PLLCON must be modified.The external clock uses P0.7 and XCLK.

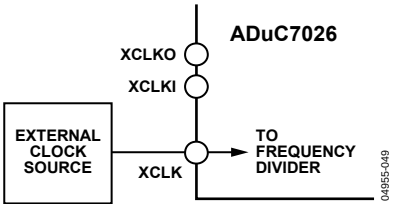


Figure 93. Connecting an External Clock Source

Using an external clock source, the ADuC7019/20/21/22/24/25/26/27/28/29-specified operational clock speed range is 50 kHz to 44 MHz ± 1%, which ensures correct operation of the analog peripherals and Flash/EE.

DEVELOPMENT TOOLS

PC-BASED TOOLS

Four types of development systems are available for the ADuC7019/20/21/22/24/25/26/27/28/29 family.

- The ADuC7026 QuickStart Plus is intended for new users who want to have a comprehensive hardware development environment. Because the ADuC7026 contains the superset of functions available on the ADuC7019/20/21/22/24/25/26/27/28/29, it is suitable for users who wish to develop on any of the parts in this family. All parts are fully code compatible.
- The ADuC7019, ADuC7024, and ADuC7026 QuickStart systems are intended for users who already have an emulator.

These systems consist of the following PC-based (Windows® compatible) hardware and software development tools.

Hardware

- ADuC7019/20/21/22/24/25/26/27/28/29 evaluation board
- Serial port programming cable
- RDI-compliant JTAG emulator (included in the ADuC7026 QuickStart Plus only)

Software

- Integrated development environment, incorporating assembler, compiler, and nonintrusive JTAG-based debugger
- Serial downloader software
- Example code

Miscellaneous

CD-ROM documentation

IN-CIRCUIT SERIAL DOWNLOADER

The serial downloader is a Windows application that allows the user to serially download an assembled program to the on-chip program Flash/EE memory via the serial port on a standard PC.

The UART-based serial downloader is included in all the development systems and is usable with the ADuC7019/20/21/22/24/25/26/27/28/29 parts that do not contain the I suffix in the Ordering Guide.

An I^2C based serial downloader and a USB-to-I^2C adaptor board, USB-EA-CONVZ, are also available at www.analog.com. The I^2C-based serial downloader is only usable with the part models containing the I suffix (see Ordering Guide).

ORDERING GUIDE

Model[1, 2]	ADC Channels[3]	DAC Channels	FLASH/ RAM	GPIO	Down-loader	Temperature Range	Package Description	Package Option	Ordering Quantity
ADuC7019BCPZ62I	5	3	62 kB/8 kB	14	I²C	−40°C to +125°C	40-Lead LFCSP_WQ	CP-40-9	
ADuC7019BCPZ62I-RL	5	3	62 kB/8 kB	14	I²C	−40°C to +125°C	40-Lead LFCSP_WQ	CP-40-9	2,500
ADuC7019BCPZ62IRL7	5	3	62 kB/8 kB	14	I²C	−40°C to +125°C	40-Lead LFCSP_WQ	CP-40-9	750
ADuC7020BCPZ62	5	4	62 kB/8 kB	14	UART	−40°C to +125°C	40-Lead LFCSP_WQ	CP-40-9	
ADuC7020BCPZ62-RL7	5	4	62 kB/8 kB	14	UART	−40°C to +125°C	40-Lead LFCSP_WQ	CP-40-9	750
ADuC7020BCPZ62I	5	4	62 kB/8 kB	14	I²C	−40°C to +125°C	40-Lead LFCSP_WQ	CP-40-9	
ADuC7020BCPZ62I-RL	5	4	62 kB/8 kB	14	I²C	−40°C to +125°C	40-Lead LFCSP_WQ	CP-40-9	2,500
ADuC7020BCPZ62IRL7	5	4	62 kB/8 kB	14	I²C	−40°C to +125°C	40-Lead LFCSP_WQ	CP-40-9	750
ADuC7021BCPZ62	8	2	62 kB/8 kB	13	UART	−40°C to +125°C	40-Lead LFCSP_WQ	CP-40-9	
ADuC7021BCPZ62-RL	8	2	62 kB/8 kB	13	UART	−40°C to +125°C	40-Lead LFCSP_WQ	CP-40-9	2,500
ADuC7021BCPZ62-RL7	8	2	62 kB/8 kB	13	UART	−40°C to +125°C	40-Lead LFCSP_WQ	CP-40-9	750
ADuC7021BCPZ62I	8	2	62 kB/8 kB	13	I²C	−40°C to +125°C	40-Lead LFCSP_WQ	CP-40-9	
ADuC7021BCPZ62I-RL	8	2	62 kB/8 kB	13	I²C	−40°C to +125°C	40-Lead LFCSP_WQ	CP-40-9	2,500
ADuC7021BCPZ32	8	2	32 kB/4 kB	13	UART	−40°C to +125°C	40-Lead LFCSP_WQ	CP-40-9	
ADuC7021BCPZ32-RL7	8	2	32 kB/4 kB	13	UART	−40°C to +125°C	40-Lead LFCSP_WQ	CP-40-9	750
ADuC7022BCPZ62	10		62 kB/8 kB	13	UART	−40°C to +125°C	40-Lead LFCSP_WQ	CP-40-9	
ADuC7022BCPZ62-RL7	10		62 kB/8 kB	13	UART	−40°C to +125°C	40-Lead LFCSP_WQ	CP-40-9	750
ADuC7022BCPZ32	10		32 kB/4 kB	13	UART	−40°C to +125°C	40-Lead LFCSP_WQ	CP-40-9	
ADuC7022BCPZ32-RL	10		32 kB/4 kB	13	UART	−40°C to +125°C	40-Lead LFCSP_WQ	CP-40-9	2,500
ADuC7024BCPZ62	10	2	62 kB/8 kB	30	UART	−40°C to +125°C	64-Lead LFCSP_VQ	CP-64-1	
ADuC7024BCPZ62-RL7	10	2	62 kB/8 kB	30	UART	−40°C to +125°C	64-Lead LFCSP_VQ	CP-64-1	750
ADuC7024BCPZ62I	10	2	62 kB/8 kB	30	I²C	−40°C to +125°C	64-Lead LFCSP_VQ	CP-64-1	
ADuC7024BCPZ62I-RL	10	2	62 kB/8 kB	30	I²C	−40°C to +125°C	64-Lead LFCSP_VQ	CP-64-1	2,500
ADuC7024BSTZ62	10	2	62 kB/8 kB	30	UART	−40°C to +125°C	64-Lead LQFP	ST-64-2	
ADuC7024BSTZ62-RL	10	2	62 kB/8 kB	30	UART	−40°C to +125°C	64-Lead LQFP	ST-64-2	1,000
ADuC7025BCPZ62	12		62 kB/8 kB	30	UART	−40°C to +125°C	64-Lead LFCSP_VQ	CP-64-1	
ADuC7025BCPZ62-RL	12		62 kB/8 kB	30	UART	−40°C to +125°C	64-Lead LFCSP_VQ	CP-64-1	2,500
ADuC7025BCPZ32	12		32 kB/4 kB	30	UART	−40°C to +125°C	64-Lead LFCSP_VQ	CP-64-1	
ADuC7025BCPZ32-RL	12		32 kB/4 kB	30	UART	−40°C to +125°C	64-Lead LFCSP_VQ	CP-64-1	2,500
ADuC7025BSTZ62	12		62 kB/8 kB	30	UART	−40°C to +125°C	64-Lead LQFP	ST-64-2	
ADuC7025BSTZ62-RL	12		62 kB/8 kB	30	UART	−40°C to +125°C	64-Lead LQFP	ST-64-2	1,000
ADuC7026BSTZ62	12	4	62 kB/8 kB	40	UART	−40°C to +125°C	80-Lead LQFP	ST-80-1	
ADuC7026BSTZ62-RL	12	4	62 kB/8 kB	40	UART	−40°C to +125°C	80-Lead LQFP	ST-80-1	1,000
ADuC7026BSTZ62I	12	4	62 kB/8 kB	40	I²C	−40°C to +125°C	80-Lead LQFP	ST-80-1	
ADuC7026BSTZ62I-RL	12	4	62 kB/8 kB	40	I²C	−40°C to +125°C	80-Lead LQFP	ST-80-1	1,000
ADuC7027BSTZ62	16		62 kB/8 kB	40	UART	−40°C to +125°C	80-Lead LQFP	ST-80-1	
ADuC7027BSTZ62-RL	16		62 kB/8 kB	40	UART	−40°C to +125°C	80-Lead LQFP	ST-80-1	1,000
ADuC7027BSTZ62I	16		62 kB/8 kB	40	I²C	−40°C to +125°C	80-Lead LQFP	ST-80-1	
ADuC7027BSTZ62I-RL	16		62 kB/8 kB	40	I²C	−40°C to +125°C	80-Lead LQFP	ST-80-1	1,000
ADuC7028BBCZ62	8	4	62 kB/8 kB	30	UART	−40°C to +125°C	64-Ball CSP_BGA	BC-64-4	
ADuC7028BBCZ62-RL	8	4	62 kB/8 kB	30	UART	−40°C to +125°C	64-Ball CSP_BGA	BC-64-4	2,500
ADuC7029BBCZ62	7	4	62 kB/8 kB	22	UART	−40°C to +125°C	49-Ball CSP_BGA	BC-49-1	
ADuC7029BBCZ62-RL	7	4	62 kB/8 kB	22	UART	−40°C to +125°C	49-Ball CSP_BGA	BC-49-1	4,000
ADuC7029BBCZ62I	7	4	62 kB/8 kB	22	I²C	−40°C to +125°C	49-Ball CSP_BGA	BC-49-1	
ADuC7029BBCZ62I-RL	7	4	62 kB/8 kB	22	I²C	−40°C to +125°C	49-Ball CSP_BGA	BC-49-1	4,000